Title (en)

ELECTRONIC HYBRID COMPONENT AND METHOD FOR THE PRODUCTION THEREOF

Title (de)

ELEKTRONISCHES HYBRID-BAUELEMENT UND VERFAHREN ZU SEINER HERSTELLUNG

Title (fr)

COMPOSANT ELECTRONIQUE HYBRIDE ET PROCEDE PERMETTANT DE LE PRODUIRE

Publication

**EP 1036416 A1 20000920 (DE)**

Application

**EP 97954329 A 19971203**

Priority

- DE 9702812 W 19971203
- DE 19720300 A 19970515

Abstract (en)

[origin: DE19720300A1] A hybrid electronic component, with a chip-on-chip arrangement, has a carrier substrate with a cavity provided with an insulating layer and an overlying metal layer, an implanted chip being electrically contacted by the metal layer in the cavity. Preferably, the top of the implanted chip is coplanar with the substrate surface, and the metal layer is a multilayer having an oxidation resistant upper metal layer. The carrier substrate is preferably an optical pin diode array with diode areas grouped around an implanted LED (2), the upper edge of the LED preferably lying a few microns below the plane of the diode areas. Also claimed is a method of producing the above component by: (a) anisotropically etching a recess in the carrier substrate; and (b) structuring to produce conductive connections between the recess and conductor line structures on the planar face by means of a multiple metallisation system.

IPC 1-7

**H01L 25/18**; H01L 29/06; H01L 25/16

IPC 8 full level

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CPC (source: EP)

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Citation (search report)

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